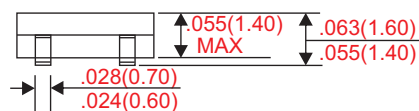
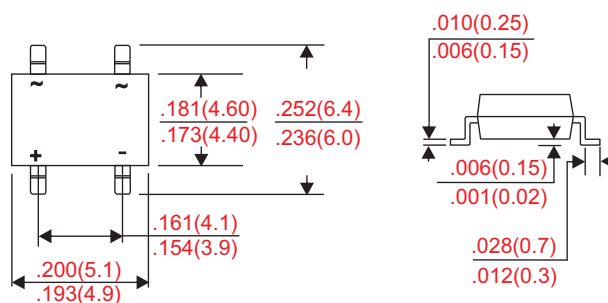


### ■ Features

- Rating to 1000V PRV.
- Ideal for printed circuit board.
- Ideal for automated replacement.
- Reliable low cost construction utilizing molded plastic technology results in inexpensive product.
- Glass passivated chip junctions.
- UL recognized file # E321971
- High temperature soldering guaranteed:  
260°C /10 seconds
- Suffix "G" indicates Halogen-free part, ex.AB102SG.

### ■ Outline

ABS



Dimensions in inches and (millimeters)

### ■ Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, ABS
- Terminals : Solder plated, solderable per  
MIL-STD-750, Method 2026
- Polarity : Symbol molded on body

### ■ Maximum ratings and electrical characteristics

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Parameter	Conditions	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	on glass-epoxy PCB at $T_A = 25^\circ\text{C}$ on aluminum substrate at $T_A = 25^\circ\text{C}$	$I_O$			0.8 1.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC method)	$I_{FSM}$			30	A
Reverse current	$V_R = V_{RRM}$ $T_A = 25^\circ\text{C}$ $V_R = V_{RRM}$ $T_A = 125^\circ\text{C}$	$I_R$			5.0 500	uA
Storage temperature		$T_{STG}$	-55		+150	°C

Symbol	Marking code	Max. repetitive peak reverse voltage $V_{RRM}$ (V)	Max. RMS voltage $V_{RMS}$ (V)	Max. DC blocking voltage $V_R$ (V)	Max. forward voltage @0.4A, $T_A = 25^\circ\text{C}$ $V_F$ (V)	Max. forward voltage @0.5A, $T_A = 25^\circ\text{C}$ $V_F$ (V)	Operating temperature $T_J$ (°C)
ABS102S	ABS102S	200	140	200	0.95	1.0	-55 ~ +150
ABS104S	ABS104S	400	280	400			
ABS106S	ABS106S	600	420	600			
ABS108S	ABS108S	800	560	800			
ABS110S	ABS110S	1000	700	1000			

### ■ Rating and characteristic curves

FIG.1-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT PER

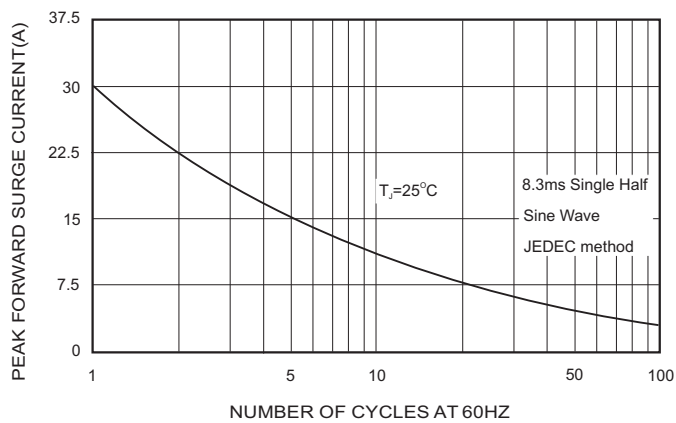


FIG.2-MAXIMUM FORWARD CURRENT DERATING CURVE

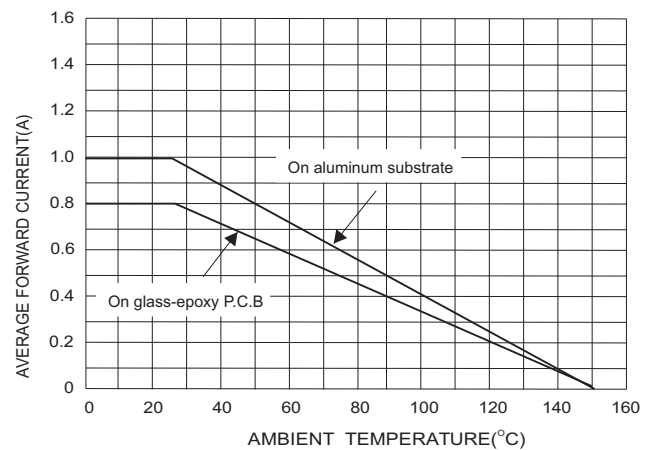


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS PER BRIDGE ELEMENT

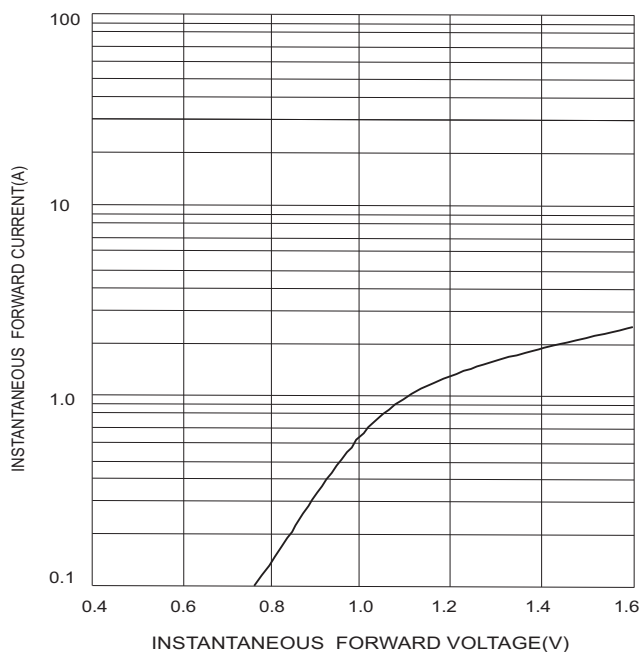
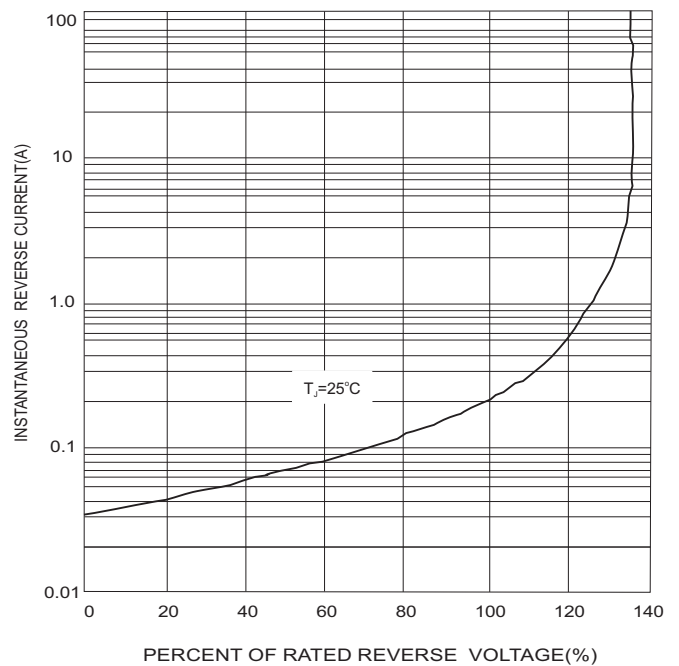
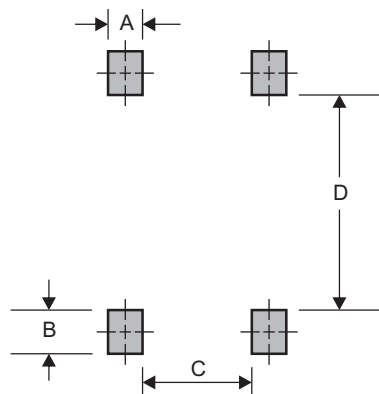


FIG.4-TYPICAL REVERSE CHARACTERISTICS PER BRIDGE ELEMENT



### ■ MDS(TO-269AA) foot print



A	B	C	D
0.024 (0.60)	0.024 (0.60)	0.132 (3.35)	0.193 (4.90)

Dimensions in inches and (millimeters)

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